

SO-8

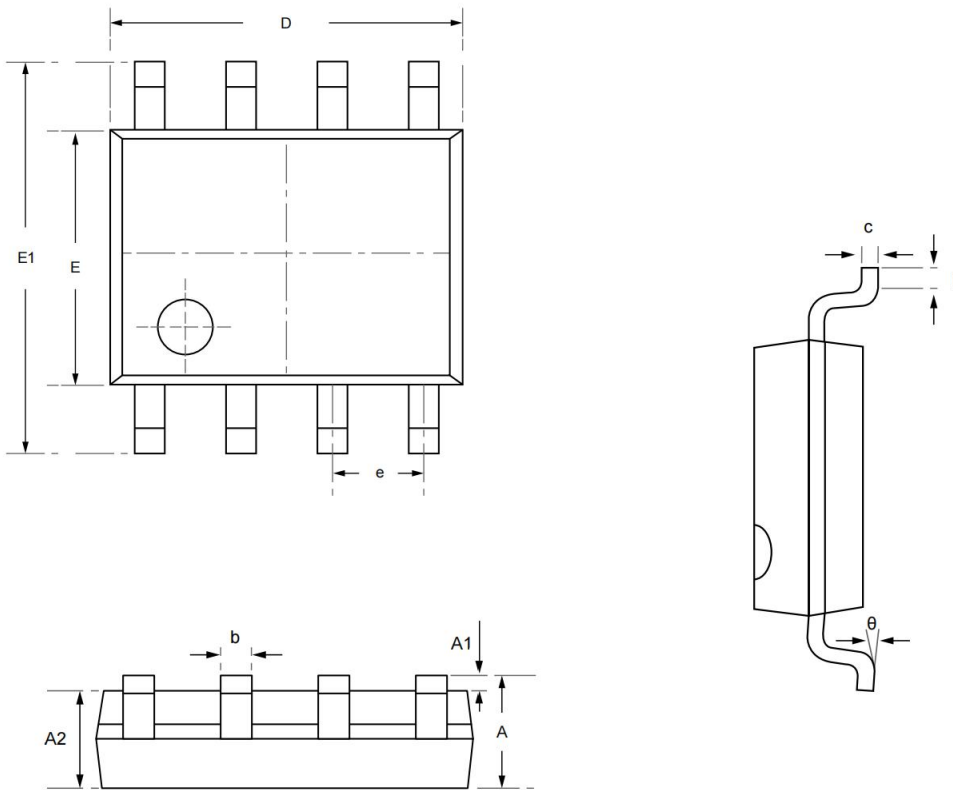
**Plastic, surface-mounted package; 8 terminals;
1.27 mm pitch; 4.9 mm x 3.9 mm x 1.75 mm body**
塑料表面贴装封装；8 引脚；间距 1.27 mm；
封装本体尺寸 4.9 mm x 3.9 mm x 1.75 mm

1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	SO-8
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	1.27mm pitch; 4.9mm × 3.9mm × 1.75mm body 相邻引脚中心距为 1.27mm，封装本体（不含引脚）尺寸为 4.9mm × 3.9mm × 1.75mm
Terminals Compliance 引脚合规	8 terminals, Tin Plated Leads, Solderable per MILSTD-202, Method 208 ^③ 8 个镀锡引脚，可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.08 grams (Approximate) 约 0.08 克

2. Package Outline Dimensions 封装外形尺寸

SO-8



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	1.35	1.75
A1	0.10	0.25
A2	1.25	1.55
b	0.28	0.48
c	0.17	0.25
D	4.80	5.00
E	3.80	4.00
E1	5.80	6.20
e	1.27(Typ.)	-
L	0.40	1.27
θ	0°	8°

3. Suggested Pad Layout 推荐焊盘布局

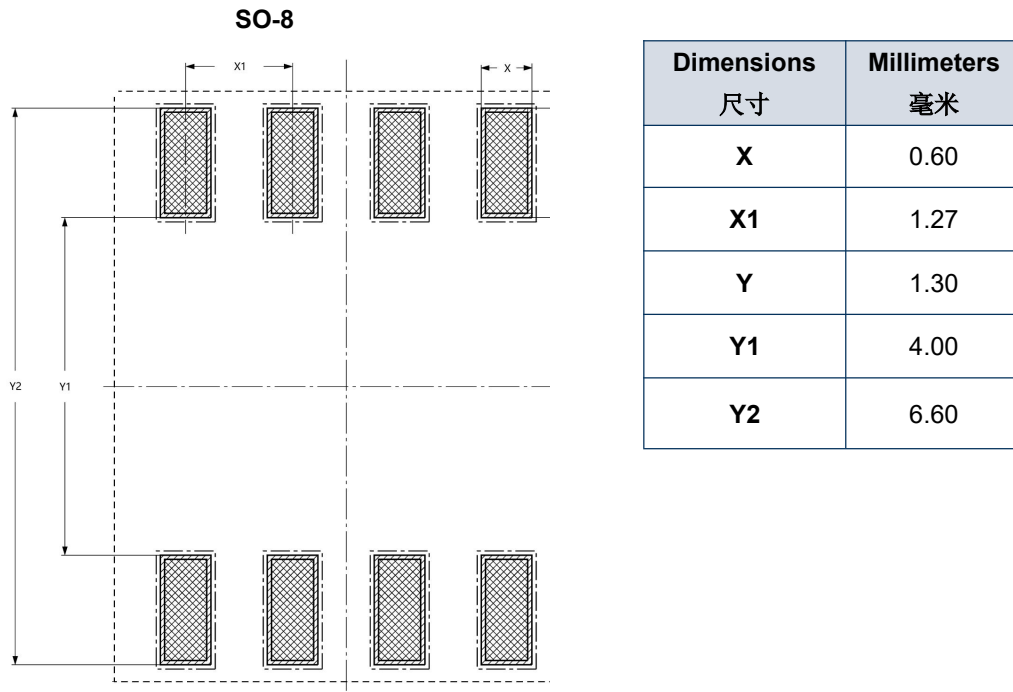


Fig. Soldering footprint for SO-8

图 SO-8 的引脚焊接

4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
13	12	2500

Note:

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

说明：上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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